### San Diego APCD

## **Emissions Inventory Request Instructions**

## **CHEMICAL PROCESSING TANKS – ELECTROPLATING**

Please refer to the general instructions for guidance regarding the following sections: Reporting Year, Facility Identification, Permit Information, Device Information, Stack / Ducted Emissions and Fugitive Release Emissions.

#### **MATERIAL / PROCESS INFORMATION**

Fill in all the data fields. Complete all blanks using the specified units. Report each individual tank/process separately.

## **CALCULATION METHOD SELECTION**

- K02-X01 Decorative Electroplating-Chromium-Uncontrolled
- K02-X02 Decorative Electroplating-Chromium-Wet Scrubber
- K02-X03 Decorative Electroplating-Chromium-Chemical Fume Suppressant
- K02-X04 Decorative Electroplating-Chromium-HEPA Filter
- K02-X08 Decorative Electroplating-Chromium-Site Specific Factors-After Controls
- K02-X09 Decorative Electroplating-Chromium-General Emission Factor Procedure
- K02-X10 Anodizing/Hard Electroplating-Chromium-Uncontrolled
- K02-X11 Anodizing/Hard Electroplating-Chromium-Wet Scrubber
- K02-X12 Anodizing/Hard Electroplating-Chromium-Chemical Fume Suppressant
- K02-X13 Anodizing/Hard Electroplating-Chromium-HEPA Filter
- K02-X18 Anodizing/Hard Electroplating-Chromium-Site Specific Factors-After Contr
- K02-X19 Anodizing/Hard Electroplating-Chromium-General Emission Factor Procedure
- K02-X20 Electroplating-Cadmium-Uncontrolled
- K02-X21 Electroplating-Cadmium-Wet Scrubber
- K02-X22 Electroplating-Cadmium-Chemical Fume Suppressant
- K02-X23 Electroplating-Cadmium-HEPA Filter
- K02-X28 Electroplating-Cadmium-Site Specific Factors-After Controls
- K02-X29 Electroplating-Cadmium-General Emission Factor Procedure
- K02-X30 Electroplating-Cadmium Cyanide-Uncontrolled
- K02-X31 Electroplating-Cadmium Cyanide-Wet Scrubber
- K02-X32 Electroplating-Cadmium Cyanide-Chemical Fume Suppressant
- K02-X33 Electroplating-Cadmium Cyanide-HEPA Filter
- K02-X38 Electroplating-Cadmium Cyanide-Site Specific Factors-After Controls
- K02-X39 Electroplating-Cadmium Cyanide-General Emission Factor Procedure
- K02-X40 Electroplating-Nickel-Uncontrolled
- K02-X41 Electroplating-Nickel-Wet Scrubber
- K02-X42 Electroplating-Nickel-Chemical Fume Suppressant
- K02-X43 Electroplating-Nickel-HEPA Filter
- KO2-X48 Electroplating-Nickel-Site Specific Factors-After Controls
- K02-X49 Electroplating-Nickel-General Emission Factor Procedure
- K02-X50 Electroplating-Copper-Uncontrolled
- K02-X51 Electroplating-Copper-Wet Scrubber
- K02-X52 Electroplating-Copper-Chemical Fume Suppressant
- K02-X53 Electroplating-Copper-HEPA Filter
- K02-X58 Electroplating-Copper-Site Specific Factors-After Controls

- K02-X59 Electroplating-Copper-General Emission Factor Procedure
- K02-X60 Electroplating-Copper Cyanide-Uncontrolled
- K02-X61 Electroplating-Copper Cyanide-Wet Scrubber
- K02-X62 Electroplating-Copper Cyanide-Chemical Fume Suppressant
- K02-X63 Electroplating-Copper Cyanide-HEPA Filter
- KO2-X68 Electroplating-Copper Cyanide-Site Specific Factors-After Controls
- K02-X69 Electroplating-Copper Cyanide-General Emission Factor Procedure
- K02-X70 Electroplating-Copper Sulfate-Uncontrolled
- K02-X71 Electroplating-Copper Sulfate-Wet Scrubber
- K02-X72 Electroplating-Copper Sulfate-Chemical Fume Suppressant
- K02-X73 Electroplating-Copper Sulfate-HEPA Filter
- KO2-X78 Electroplating-Copper Sulfate-Site Specific Factors-After Controls
- K02-X79 Electroplating-Copper Sulfate-General Emission Factor Procedure
- K02-X99 Electroplating-Other-General Emission Factor Procedure

**Air Agitation:** Identify if air agitation is used. If air agitation is used, add a device with a K01-Chemical Process Tank calc method.

Contains HCI (hydrochloric acid): Identify tank solutions containing hydrochloric acid.

**Contains HF (hydrofluoric acid):** Identify tank solutions containing hydrofluoric acid.

**Suppressants Name (provide name):** Provide the trade name or material name of the mist suppressant used. If no suppressant is used, select 'No Controls'.

Max. Current Usage (amp-hrs/hour): Report the maximum amount of amps-hr used in a single hour, during the reporting period.

**Capture and Control Equipment:** Identify any capture systems used and cite efficiencies. Control equipment is built into the calculator chosen and the default emissions factors. Unless previously supplied for emissions inventory or listed in the permit description, all efficiencies must be justified with supporting documentation. Upload supporting documentation to EIS before submittal.

# **Device Operating Schedule:**

Daily Operation (hours/day): Report the average amount of hours the device operates in a typical day.

Weekly Operation (days/week): Report the average number of days the device operates in a typical week.

Annual Operation (days/year): Report the number of days the device operated during the Reporting Year.

# POLLUTANT NAME (lbs pollutant/amp-hr)

Identify pollutants emission factors based on the composition of the plating solution. Provide emission factors for each pollutant (lbs pollutant/ amp-hr) with supporting documentation. Input emission factors into EIS for submission either through direct entry through the 'Enter Emissions Inventory Data' module or through upload of an EIQ spreadsheet.